

## ABSTRACT

A semiconductor component includes a thinned  
5 semiconductor die having protective polymer layers on up to  
six surfaces. The component also includes contact bumps on  
the die embedded in a circuit side polymer layer, and  
terminal contacts on the contact bumps in a dense area array.  
A method for fabricating the component includes the steps of  
10 providing a substrate containing multiple dice, forming  
trenches on the substrate proximate to peripheral edges of  
the dice, and depositing a polymer material into the  
trenches. In addition, the method includes the steps of  
planarizing the back side of the substrate to contact the  
15 polymer filled trenches, and cutting through the polymer  
trenches to singulate the components from the substrate.  
Prior to the singulating step the components can be tested  
and burned-in while they remain on the substrate.